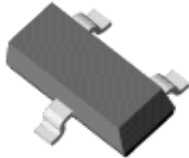




SEMICONDUCTOR Small Signal Products

MATERIAL CONTENT LIST

PACKAGE FAMILY: **SOT-23**
 DATE: **21-Apr-2009**
 REVISION: **13**



**RoHS
COMPLIANT**



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
Mold compound 76.7% (raw material before curing)	Silicon Fused	60676-86-0	5.02	74.0%	567313
	Epoxy Resin	29690-82-2	0.68	10.0%	76664
	Phenol Novalac	9003-35-4	0.68	10.0%	76664
	Mixed Siloxanes	2530-83-8	0.20	3.0%	22999
	Antimony Trioxide	1309-64-4	0.07	1.0%	7666
	Brominated Compound	40039-93-8	0.07	1.0%	7666
	Carbon	7440-44-0	0.07	1.0%	7666
	TOTAL			6.78	
Lead frame 20.7%	Si	7440-21-3	0.005	0.3%	565
	Mn	7439-96-5	0.013	0.7%	1470
	Ni	7440-02-0	0.74	40.2%	83109
	Co	7440-48-4	0.009	0.5%	1018
	Fe	7439-89-6	1.005	55.0%	113639
	Cr	7440-47-3	0.002	0.1%	226
	C	7440-44-0	0.0004	0.02%	45
	Cu	7440-50-8	0.002	0.1%	226
	Ag	7440-22-4	0.057	3.1%	6445
	TOTAL			1.828	
Terminal finish 1.4%	Sn	7440-31-5	0.12	100.0%	13569
	TOTAL			0.12	
Silicon chip 1.1%	Si	7440-21-3	0.092	91.6%	10403
	SiO ₂	14808-60-7	0.0004	0.4%	45
	Au	7440-57-5	0.008	8.0%	905
	And / or traces of As, Ag, Ti, Al, Ni, Pd, Cu				
TOTAL			0.100		
Bond wire 0.2%	Au	7440-57-5	0.015	100.0%	1696
	TOTAL			0.015	
Total weight			8.844		

Remark: Total weight range ± 10%
 Reflow Soldering acc. J-STD-020D
 Material Analyses Reports available on request